

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

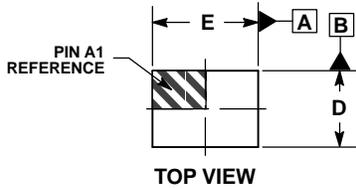
ON Semiconductor®



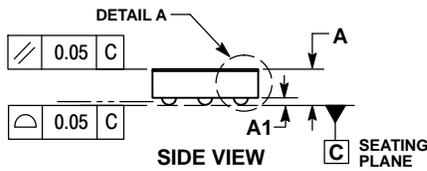
SCALE 4:1

WLCSP6 0.85x1.17x0.40
CASE 567TL
ISSUE O

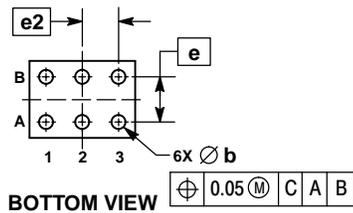
DATE 14 MAR 2017



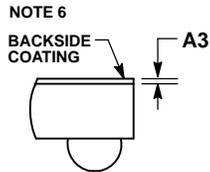
TOP VIEW



SIDE VIEW



BOTTOM VIEW



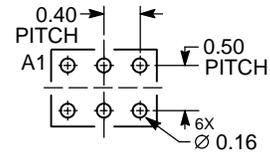
DETAIL A
OPTIONAL CONSTRUCTION

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	---	---	0.40
A1	0.05	0.08	0.11
A3	0.025 REF		
b	0.11	0.16	0.21
D	0.80	0.85	0.90
E	1.12	1.17	1.22
e	0.50 BSC		
e2	0.40 BSC		

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP6 0.85X1.17X0.40	PAGE 1 OF 2

